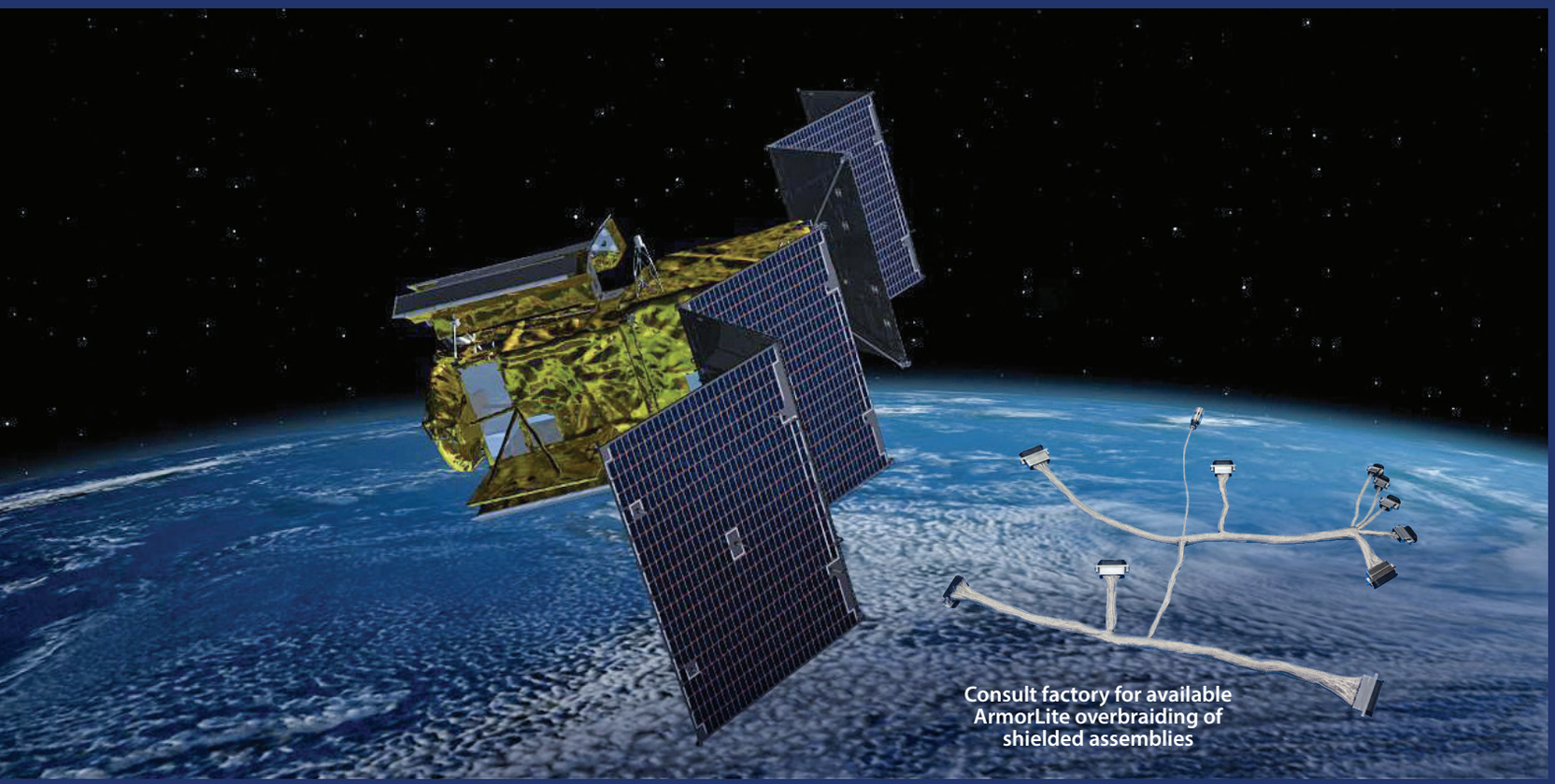
A GLENAIR SIGNATURE

High-Rel Cable Assembly

CRITICAL COMPONENT

ARMORLITE™

Flexible braided straps for EMI noise supression and equipotential bonding, plus lightweight EMI/RFI cable shielding



ArmorLite is an innovative material ideally suited for cable shielding, ESD bonding, and surge current grounding. Nickel- and silver-clad stainless steel microfilament material saves significant weight compared to standard plated QQ-B-575 copper material. A 100% ArmorLite bond strap, for example, is more than 70% lighter than a conventional plated copper solution of the same length.

Flexible, durable ArmorLite ESD bond straps are supplied in materials optimized for the moderate current and resistance requirements of electrical potential bonding in space applications. ArmorLite 100% is the lightest weight solution. ArmorLite CF is a special construction designed for optimal corrosion protection. ArmorLite Ag silver-plated microfilament SST braid offers the lowest electrical resistance.

- **Ultra-lightweight EMI/RFI braiding material for high-temperature applications -80°C to +260°C**
- **Microfilament materials: 70% lighter than NiCu A-A-59569/QQB575**
- **Good electrical performance: shielding, conductivity, and grounding**
- **Proven performance in space: Technical Readiness Level 9**
- **Superior flexibility and "windowing" resistance**
- **Strong: 70,000 psi (min.) tensile strength**
- **NASA-STD-4005 and ECSS-E-ST-20-07 compliant**